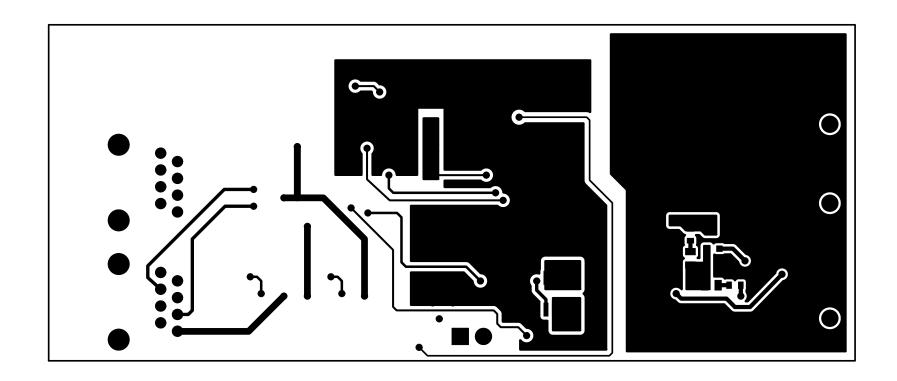
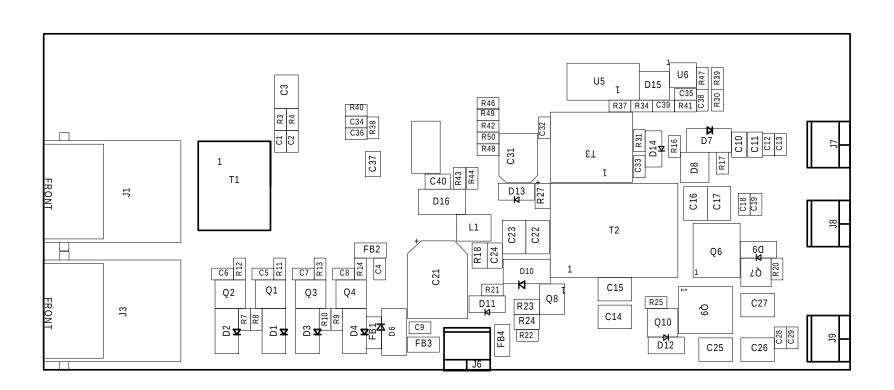


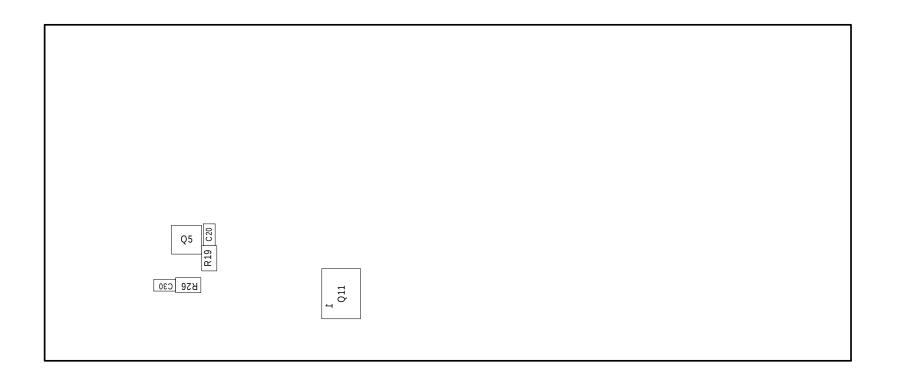
TEYNO	SINSTRUM	Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing	
ILAA	Тор		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	Bot		
Board No.	Board No. PMP8407		L1											
Date: 01-02-13	Date: 01-02-13 Filename: PMP8407_RevC Engineer: D Stra		sser PCB Dsgnr:		Dsgnr: {Name}	Mod	Modified Date: {Modification Date}						Software	PADs v9.3



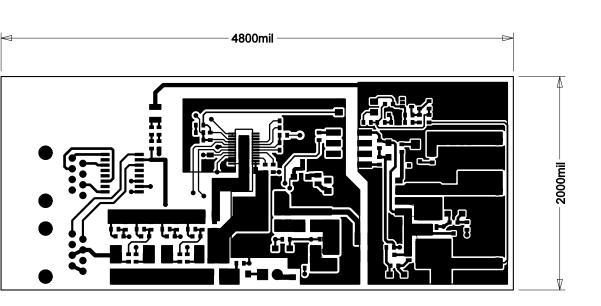
TEV	KAS INSTRUM	Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing	
	Top		Bot	Top	Bot	Top	Bot	Top	Bot	Top	Bot	T ab Drawing		
Board No.	PMP8407	Rev.			L2									
Date: 01-02-13	Date: 01-02-13 Filename: PMP8407_RevC Engineer: D Stras		ısser	PCB Dsgnr: {Name}		Modified Date: {Modification Date}							Software	PADs v9.3



TEYNO	SINSTRUM	Coppe	Copper Layer Name			Silkscreen		S Mask		P Mask		mbly	Fab Drawing	
ILAA	Тор		Bot	Top	Bot	Top	Bot	Тор	Bot	Top	Bot	Bot		
Board No.	Board No. PMP8407		L1									ТА		
Date: 01-02-13 Filename: PMP8407_RevC Engineer: D Str		sser PCB Dsgnr: {Name}		Mod	ified Date: {	(Modificati	on Date}				Software	PADs v9.3		



ob Drawing	Assembly	4	Nask	Р	l ask	S	een	enle 21	ayer	per L	оО		TEXAS INSTRUMENTS							
Fab Drawing	ot	l qo	ot 7	g qc	ot T	∃ q	οГ	Bot	qo	Τ	Bot	Гор	Т							
	ΑB										L2			Э	Rev.	3407	Board No. PMPE			
	PADs v9.3	Software				Date}	fication	tiboM} ^{::}	lified Date	bo M	Dsgnr: {Name}	PCB	sser	Engineer: D Stra		Filename: PMP8407_RevC	Date: 01-02-13			



TEVAC	Copper Layer Name			Silkscreen		S Mask		P Mask		Assembly		Fab Drawing			
TEXAS INSTRUMENTS			Top		Bot	Top	Bot	Top	Bot	Top	Bot	Тор	Bot	Fab Drawing	
PMP8407 C		L1											FB		
Date: 01-02-13 Filename: PMP8407_RevC Engineer: D Stras		sser PCB Dsgnr: {Name}		Мо	dified Date:	Modificati	on Date}				Software	PADs v9.3			

FABRICATION CHART											
FINISHED THICKNESS	SILKSCREEN	SOLDERMA	ASK	FINISHED COPPER WEIGHT							
□ 0.031	■ LAYER 1	■ LAYER	1	☐ 1 OZ.							
■ 0.062	■ LAYER 2	■ LAYER	2	■ 2 OZ.							
□ 0.093	■ NONE	☐ NONE		☐ OTHER							
□ 0.125											
DESIGN	TRACE/GAP S	SPACING	LAYER COUNT								
□ SMD	0.010/0.01	.0		SINGLE SIDED							
☐ THRU-HOLE	0.008/0.00	17		2 LAYER							
■ MIX	0.006/0.00	6		4 LAYER							
				OTHER							

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS

AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.

PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR

2. BASE LAMINATE:

EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 320 Deg c.

GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP,

COMPLIANT WITH LEAD FREE PROCESS.

3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN

ACCORDANCE WITH IPC-SM-840. COLOR: GRÉEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY

AS A RESULT.

4. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES

SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES.

5. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN.

THICK COPPER.

6. FINISH: PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu,

WITH RMA FLUX, 0.0003" to .0005" THICK ALL EXPOSED AREAS

AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.

7. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.

8. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK).

LOCATION OPTIONAL.

9. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.

10. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS

INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.

11. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS

MUST BE COVERED WITH SOLDERMASK.

13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION

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